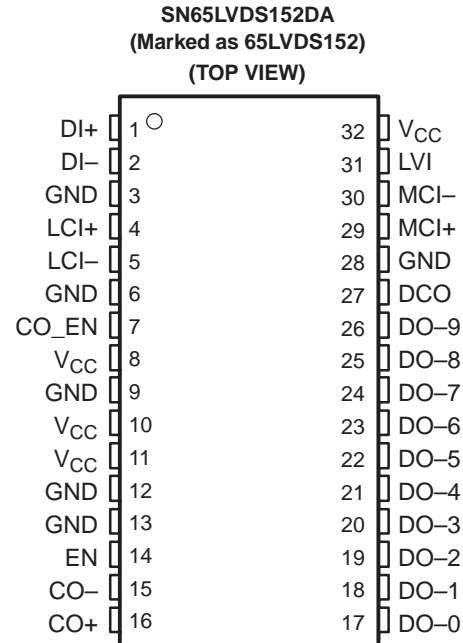# MuxIt™ RECEIVER-DESERIALIZER

Check for Samples: SN65LVDS152

FEATURES

- **A Member of the MuxIt™ Serializer-Deserializer Building-Block Chip Family**
- **Supports Deserialization of One Serial Link Data Channel Input at Rates up to 200 Mbps**
- **PLL Lock/Valid Input Provided to Enable Parallel Data and Clock Outputs**
- **Cascadable With Additional SN65LVDS152 MuxIt Receiver-Deserializers for Wider Parallel Output Data Channel Widths**
- **LVDS Compatible Differential Inputs and Outputs Meet or Exceed the Requirements of ANSI TIA/EIA-644-A**
- **LVDS Input and Output ESD Protection Exceeds 12 kV HBM**
- **LVTTL Compatible Inputs for Lock/Valid and Enables Are 5-V Tolerant**
- **Operates With 3.3-V Supply**
- **Packaged in 32-Pin DA Thin Shrink Small-Outline Package With 26-Mil Terminal Pitch**

SN65LVDS152DA
(Marked as 65LVDS152)
(TOP VIEW)

Pin	Name		Pin	Name
1	DI+		32	V_{CC}
2	DI−		31	LVI
3	GND		30	MCI−
4	LCI+		29	MCI+
5	LCI−		28	GND
6	GND		27	DCO
7	CO_EN		26	DO−9
8	V_{CC}		25	DO−8
9	GND		24	DO−7
10	V_{CC}		23	DO−6
11	V_{CC}		22	DO−5
12	GND		21	DO−4
13	GND		20	DO−3
14	EN		19	DO−2
15	CO−		18	DO−1
16	CO+		17	DO−0

DESCRIPTION

MuxIt is a family of general-purpose, multiple-chip building blocks for implementing parallel data serializers and deserializers. The system allows for wide parallel data to be transmitted through a reduced number of transmission lines over distances greater than can be achieved with a single-ended (e.g., LVTTL or LVCMOS) data interface. The number of bits multiplexed per transmission line is user selectable, allowing for higher transmission efficiencies than with other existing fixed ratio solutions. MuxIt utilizes the LVDS (TIA/EIA-644-A) low voltage differential signaling technology for communications between the data source and data destination.

The MuxIt family initially includes three devices supporting simplex communications: the SN65LVDS150 phase locked loop frequency multiplier, the SN65LVDS151 serializer-transmitter, and the SN65LVDS152 receiver-deserializer.

The SN65LVDS152 consists of three LVDS differential transmission line receivers, an LVDS differential transmission line driver, a 10-bit serial-in/parallel-out shift register, plus associated input and output buffers. It receives serialized data over an LVDS transmission line link, deserializes (demultiplexes) it, and delivers it on parallel data outputs, DO−0 through DO−9. Data received over the link is clocked at a factor of M times the original parallel data frequency. The multiplexing ratio M, or number of bits per data clock cycle, is programmed with configuration pins (M1 → M5) on the companion SN65LVDS150 MuxIt programmable PLL frequency multiplier. Up to 10 bits of data may be deserialized and output by each SN65LVDS152. Two or more SN65LVDS152 units may be connected in series (cascaded) to accommodate wider parallel data paths for higher serialization values. The range of multiplexing ratio M supported by the SN65LVDS150 MuxIt programmable PLL frequency multiplier is between 4 and 40. Table 1 shows some of the combinations of LCI and MCI supported by the SN65LVDS150 MuxIt programmable PLL frequency multiplier.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DECRIPTION (CONTINUED)

Data is serially shifted into the SN65LVDS152 shift register on the falling edges of the M-clock input (MCI). The data is latched out in parallel from the SN65LVDS152 shift register on the second rising edge after the first falling edge of the M-clock following a rising edge of the link clock input (LCI). The SN65LVDS152 includes LVDS differential line receivers for both the serialized link data stream (DI) and link clock (LCI). High-speed signals from the SN65LVDS150 MuxIt programmable frequency multiplier (MCI), plus the input and output for cascaded data (DI, CO) are carried over differential connections to minimize skew and jitter. Examples of operating waveforms for values of M = 4 and M = 10 are provided in Figure 1.

The enable input (EN) along with internal power-on reset (POR) controls the outputs. When Vcc is below 1.5 volts, or when EN is low, outputs are disabled. When V_{CC} is above 3 V and EN is high, outputs are enabled and operating to specifications.

Parallel data bits are output from DO-n outputs in an order dependent on the value of the multiplexing ratio (frequency multiplier value) M. For values of M from 4 through 10, the cascade output (CO±) is not used, and only the top M parallel outputs (DO–9 through DO–[10-M]) are used. The data bit output on DO-9 corresponds to the data bit input on DI–[M–1] of the SN65LVDS151 serializer. Likewise, the data bit output on DO-[10-M] will correspond to the data bit input on DI–0 of the SN65LVDS151 serializer.

For values of M greater than 10, the cascade output (CO±) is used to connect multiple SN65LVDS152 deserializers. In this case the higher-order unit(s) output 10 bits each of the highest numbered bits that are input into the SN65LVDS151 serializer(s). The lowest numbered input bits are output on the lowest-order SN65LVDS152 deserializer in descending order from output DO–9. The number of bits is equal to M mod(10). Table 2 reflects this information, where X = M mod(10)

Table 1. Example Combinations of LCI and MCI Supported by the SN65LVDS150 MuxIt Programmable PLL Frequency Multiplier

	LCI, MHz		MCI, MHz	
M	MINIMUM	MAXIMUM	MINIMUM	MAXIMUM
4	5	50	20	200
10	5	20	50	200
20	5	10	100	200
40	5	5	200	200

Table 2. Output Data Bits as a Function of Multiplier Value M

	X = 1	X = 2	X = 3	X = 4	X = 5	X = 6	X = 7	X = 8	X = 9	X = 0
DO-9 output bit	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6	DI-7	DI-8	DI-9
DO-8 output bit	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6	DI-7	DI-8
DO-7 output bit	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6	DI-7
DO-6 output bit	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6
DO-5 output bit	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5
DO-4 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4
DO-3 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3
DO-2 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2
DO-1 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1
DO-0 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0

Additional information on output bit ordering in cascaded applications can be found in the MuxIt Application Report.
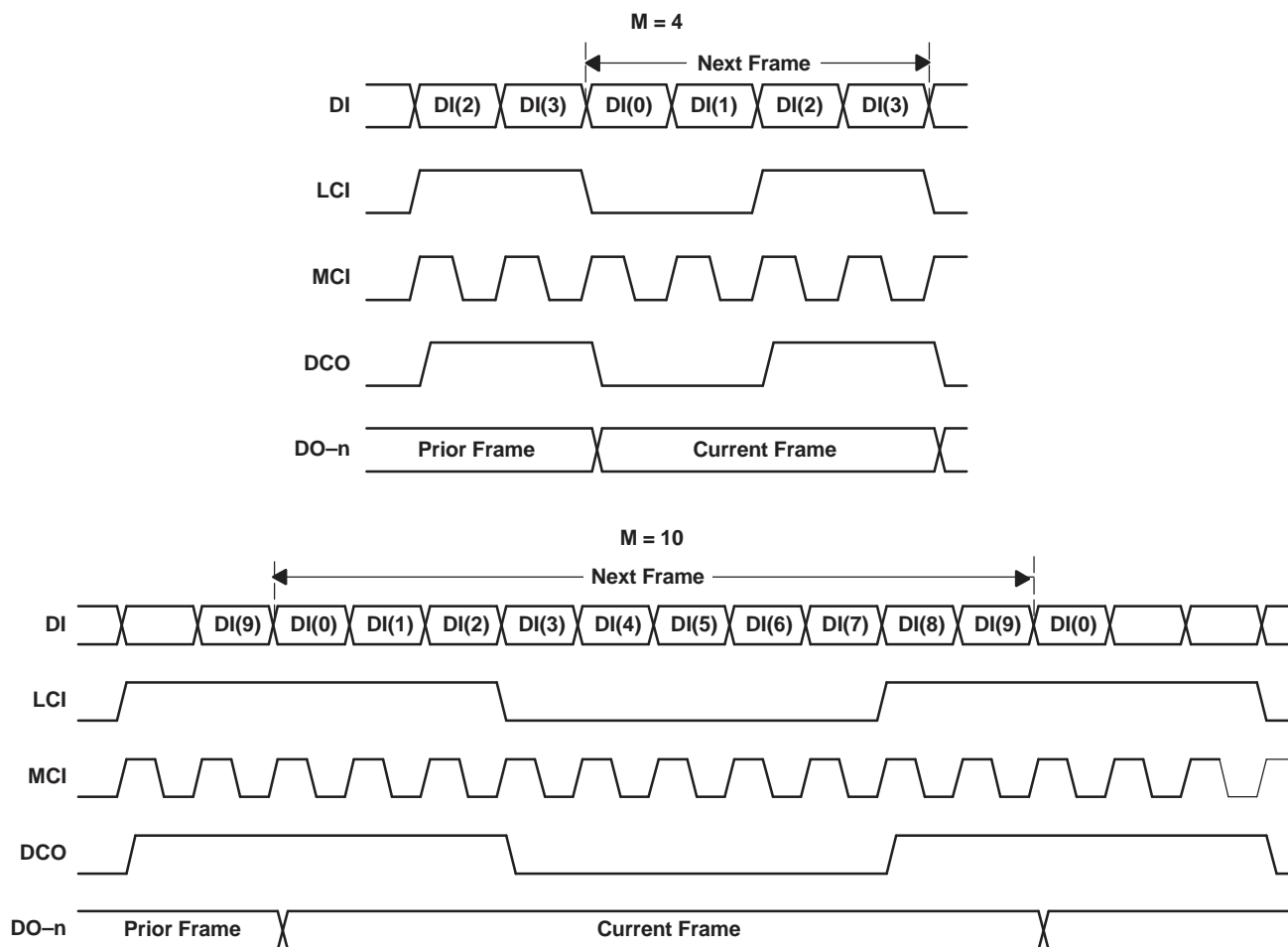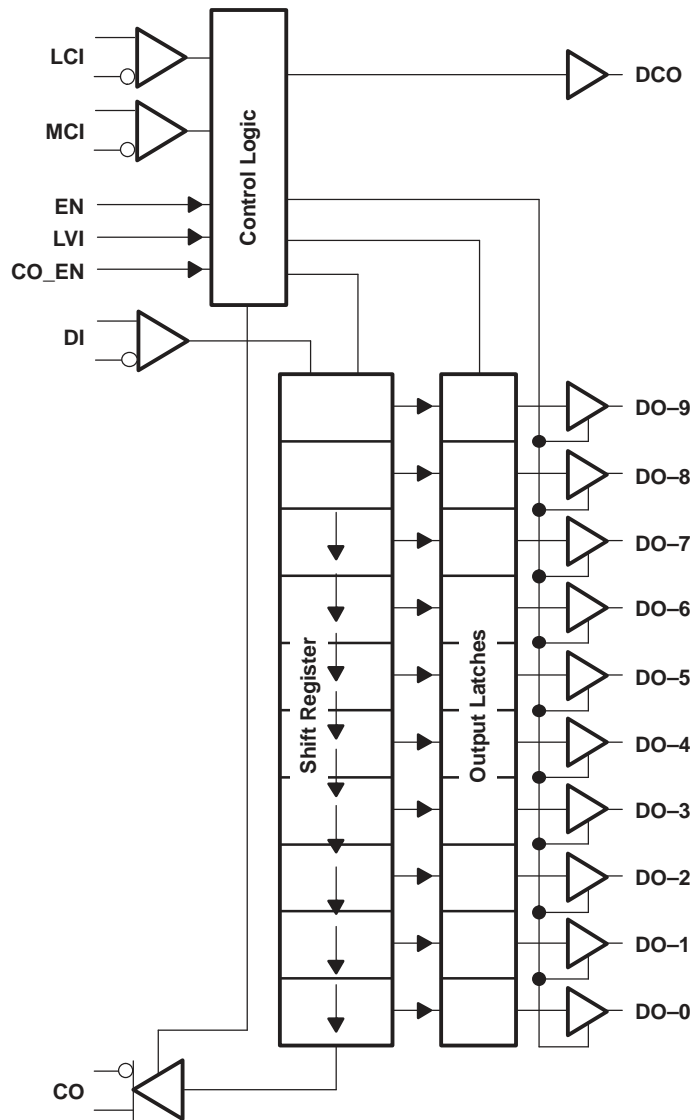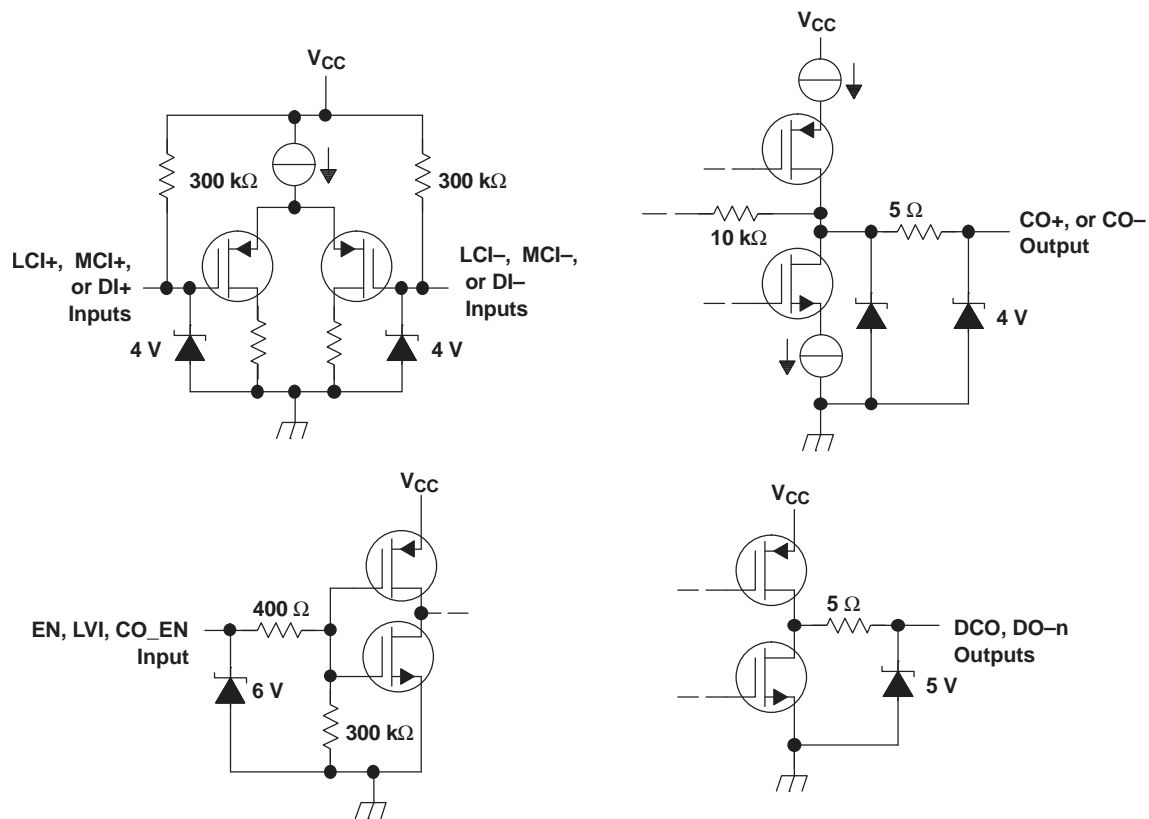

Figure 1. Operating Waveform Examples

FUNCTIONAL BLOCK DIAGRAM

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Product Folder Link(s): *SN65LVDS152*

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS

Terminal Functions

TERMINAL		I/O	LEVEL	DESCRIPTION
NAME	NO.			
CO–, CO+	15, 16	Output	LVDS	Cascade output. This is used to connect to additional SN65LVDS152 units when the multiplexing ratio M (and M-clock) value is greater than 10.
CO_EN	7	Input	LVTTL	Cascade output enable. Used to control the CO output. A high-level input enables the CO output, a low-level input disables the CO output.
DCO	27	Output	LVTTL	Data clock output. This is the recovered (original frequency) clock that is synchronized to the deserialized parallel data.
DI+, DI–	1, 2	Input	LVDS	Link data input. This is the data being received from the source end of the serialized link. Also used for cascade data input from additional SN65LVDS152 units when the multiplexing ratio M value is greater than 10.
EN	14	Input	LVTTL	Enable. Used to control overall device operation. A high-level input enables the device. A low-level input disables the device by resetting the internal latches and forcing the CO and LVTTL outputs to a high-impedance state.
GND	3, 6, 9, 12, 13, 28	Power	NA	Circuit ground
LCI+, LCI–	4, 5	Input	LVDS	Link clock input. This is the data block synchronization clock received from the source end of the serialized link.
LVI	31	Input	LVTTL	Lock/valid input. This is a signal required for proper Muxlt system operation. It is to be directly connected to the LVO output of an SN65LVDS150. It is used to inhibit the operation of this device until after the PLL has stabilized. A low level input disables the data and clock outputs, a high level input enables the outputs
MCI+, MCII–	29,30	Input	LVDS	M-clock input. This is the high frequency multiplied clock input from the local PLL frequency multiplier. It synchronizes the reception of the link data
DOI–0I–DOI–9	17-26	Output	LVTTL	Parallel data outputs. Data from the serial shift register is transferred to the output data latches in synchronization with the rising edge of LCI.
V$_{CC}$	8, 10, 11, 32	Power	NA	Supply voltage

Product Folder Link(s): SN65LVDS152

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)[1]

		UNIT
Supply voltage range, V_{CC} [2]		–0.5 V to 4 V
Input voltage range	EN, LVI, CO_EN	–0.5 V to 5.5 V
	LCI±, MCI±, DI±, CO±	–0.5 V to 4 V
Electrostatic discharge, human body model[3]	LCI±, MCI±, DI±, CO±, and GND	±12 kV
	All pins	±2 kV
Charged-device model[4]	All pins	±500 V
Continuous power dissipation		See Dissipation Rating Table
Storage temperature range		–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		260°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
(3) Tested in accordance with JEDEC Standard 22, Test Method A114-B.
(4) Tested in accordance with JEDEC Standard 22, Test Method C101.

DISSIPATION RATING TABLE

PACKAGE	$T_A ≤ 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 85°C$ POWER RATING
DA	1453 mW	11.6 mW/°C	756 mW

RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	3.3	3.6	V
V_{IH}	High-level input voltage	EN, LVI, CO_EN	2		V_{CC}	V
V_{IL}	Low-level input voltage				0.8	V
$\lvert V_{ID} \rvert$	Magnitude of differential input voltage		0.1		0.6	V
V_{IC}	Common-mode input voltage	LCI±, MCI±, DI±	$\dfrac{\lvert V_{ID} \rvert}{2}$		$2.4 - \dfrac{\lvert V_{ID} \rvert}{2}$	V
					$V_{CC} - 0.8$	V
T_A	Operating free-air temperature		40		85	°C

TIMING REQUIREMENTS

PARAMETERS		TEST CONDITIONS	MIN	MAX	UNIT
$t_{su(1)}$	Clock setup time, MCI↓ before LCI↑	See Figure 2	0		ns
$t_{su(2)}$	Clock setup time, LCI↑ before MCI↓		1		ns
$t_{su(3)}$	Link data setup time, DI before MCI↓	See Figure 3	0.3		ns
$t_{h(3)}$	Link data hold time, DI after MCI↓		0.5		ns

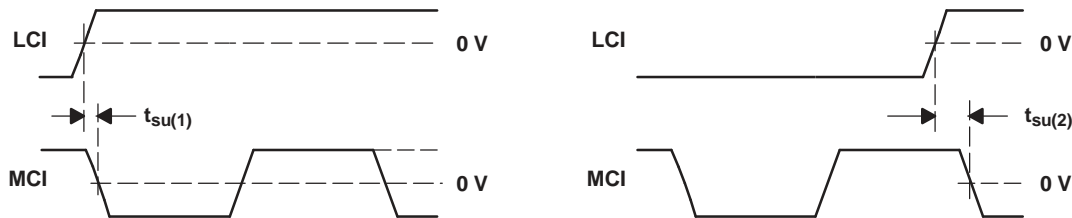Product Folder Link(s): *SN65LVDS152*

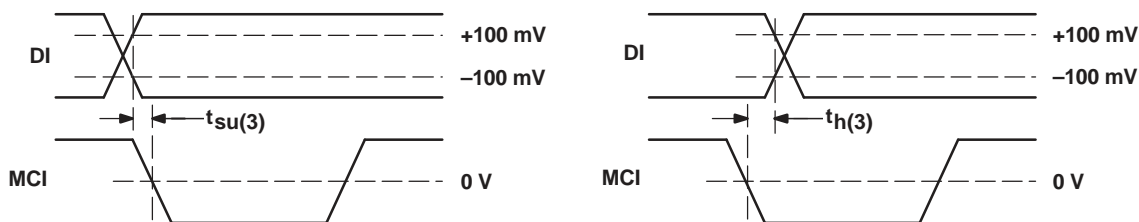**Figure 2. Link Clock Input and M-Clock Setup Time Waveforms**

Figure 3. Input Data and M-Clock Setup and Hold Time Waveforms

ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP[1]	MAX	UNIT
V_{ITH+}	Positive-going differential input voltage threshold	See Figure 4				100	mV
V_{ITH-}	Negative-going differential input voltage threshold			−100			
$|V_{OD(SS)}|$	Steady-state differential output voltage magnitude	R_L = 100 Ω, V_{ID} = ±100 mV, See Figure 5 and Figure 6		247	340	454	mV
$\Delta|V_{OD(SS)}|$	Change in steady-state differential output voltage magnitude between logic states			−50		50	mV
$V_{OC(SS)}$	Steady-stade common-mode output voltage	See Figure 7		1.125		1.375	V
$\Delta V_{OC(SS)}$	Change in steady-state common-mode output voltage between logic states			-50		50	mV
$V_{OC(PP)}$	Peak-to-peak change common-mode output voltage				50	150	mV
V_{OH}	High-level output voltage	DO–n, DCO	I_{OH} = −8 mA	2.4			V
V_{OL}	Low-level output voltage		I_{OL} = 8 mA			0.4	
I_{CC}	Supply current		Enabled, R_L = 100 Ω,		14	25	mA
			Disabled		0.5	1	
			$f_{(MCI)}$ = 200 MHz, $f_{(LCI)}$ = 20 MHz, R_L = 100 Ω, DI-n= 1010101010 at 200 Mbit/s		35	60	
I_I	Input current	LCI, MCI, DI inputs	V_I = 0 V	−2		-20	µA
			V_I = 2.4 V	−1.2			
I_{ID}	Differential input current	LCI, MCI, DI inputs	V_{IC} = 0.05 V to 2.35 V, V_{ID} = ±0.1 V	−2		2	µA
$I_{I(OFF)}$	Power-off input current	LCI, MCI, DI inputs	V_{CC} = 0 V , V_I = 3.6 V			20	µA
I_{IH}	High-level input current	EN, LVI, CO_EN	V_{IH} = 2 V			20	µA
I_{IL}	Low-level input current	EN, LVI, CO_EN	V_{IL} = 0.8 V			10	µA
I_{OS}	Short-circuit output current	CO	V_{O+} or V_{O-} = 0 V	−10		10	mA
			V_{OD} = 0 V	−10		10	mA
I_{OZ}	High-impedance output current	CO	V_O = 0 V or V_{CC}	−5		5	µA
		DO-n, DCO		−5		5	
$I_{O(OFF)}$	Power-off output current	CO	V_{CC} = 1.5 V , V_O = 3.6 V	−5		5	µA
C_I	Input capacitance	LCI, MCI, DI inputs	V_{ID} = (0.4sin(4E6πt) + 0.5) V		3		pF

(1) All typical values are at T_A = 25°C and with V_{CC} = 3.3 V.

SN65LVDS152

SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{d(1)}$	Propagation delay time, LCI↑ to DCO↑	See Figure 8		2	3	ns
$t_{d(2)}$	Delay time, MCI↑ to DO-n			3.3	5.5	
$t_{su(4)}$	Set-up time, DO-n valid to DCO↑		5			
$t_{h(4)}$	Hold time, DCO↑ to DO-n valid		5			
$t_{d(3)}$	Delay time, MCI↓ to CO	See Figure 9		2.9	4.5	ns
t_r	Differential output signal rise time, CO	R_L = 100 Ω, C_L = 10 pF, See Figure 10	0.3	0.8	1.5	ns
	Output signal rise time, DCO, DO-n	C_L = 10 pF, See Figure 11		0.6	1.5	
t_f	Differential output signal fall time, CO	R_L = 100 Ω, C_L = 10 pF, See Figure 10	0.3	0.8	1.5	ns
	Output signal fall time, DCO, DO-n	C_L = 10 pF, See Figure 11		0.6	1.5	
$t_{sk(p)}$	Pulse skew ($|t_{PHL} - t_{PLH}|$), CO	R_L = 100 Ω, C_L = 10 pF, See Figure 10		0	300	ps
t_{PZH}	Propagation delay time, high-impedance to high-level output (DCO only)	EN to DCO, DO-n, C_L = 10 pF, See Figure 12		5	15	ns
t_{PZL}	Propagation delay time, high-impedance to low-level output			5	15	
t_{PHZ}	Propagation delay time, high-level to high-impedance output			5	15	
t_{PLZ}	Propagation delay time, low-level to high-impedance output			6	15	
t_{PZH}	Propagation delay time, high-impedance to high-level output (DCO only)	LVI to DCO, DO-n C_L = 10 pF, See Figure 12		5	15	ns
t_{PZL}	Propagation delay time, high-impedance to low-level output			5	15	
t_{PHZ}	Propagation delay time, high-level to high-impedance output			5	15	
t_{PLZ}	Propagation delay time, low-level to high-impedance output			5	15	

Product Folder Link(s): SN65LVDS152

PARAMETER MEASUREMENT INFORMATION
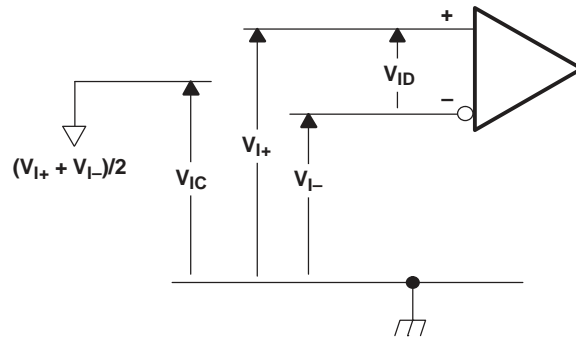
Figure 4. Receiver Voltage Definitions

Table 3. Receiver Minimum and Maximum Input Threshold Test Voltages

APPLIED VOLTAGES		RESULTING DIFFERENTIAL INPUT VOLTAGE	RESULTING COMMON-MODE INPUT VOLTAGE
V_{I+}	V_{I-}	V_{ID}	V_{IC}
1.25 V	1.15 V	100 mV	1.2 V
1.15 V	1.25 V	−100 mV	1.2 V
2.4 V	2.3 V	100 mV	2.35 V
2.3 V	2.4 V	−100 mV	2.35 V
0.1 V	0 V	100 mV	0.05 V
0 V	0.1 V	−100 mV	0.05 V
1.5 V	0.9 V	600 mV	1.2 V
0.9 V	1.5 V	−600 mV	1.2 V
2.4 V	1.8 V	600 mV	2.1 V
1.8 V	2.4 V	−600 mV	2.1 V
0.6 V	0 V	600 mV	0.3 V
0 V	0.6 V	−600 mV	0.3 V
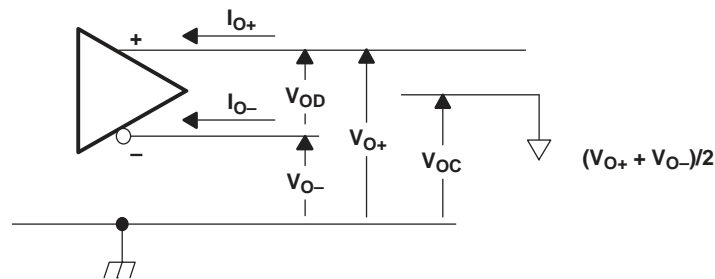
Figure 5. Driver Voltage and Current Definitions
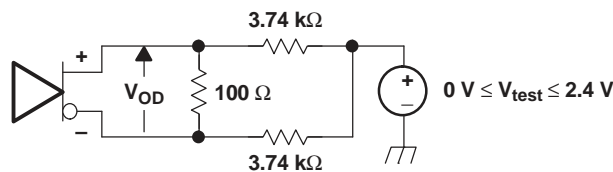
Figure 6. V_{OD} Test Circuit
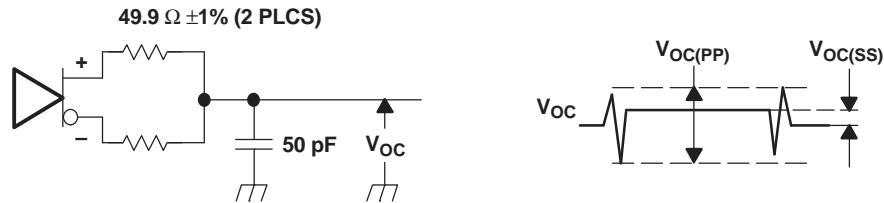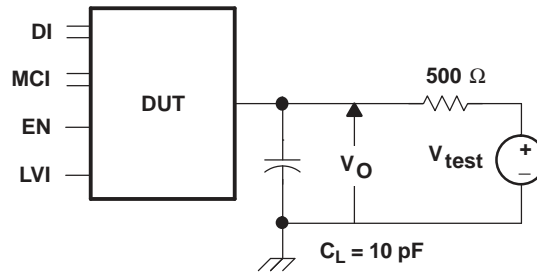
Product Folder Link(s): SN65LVDS152

A. All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, Pulse width = 500 ± 10 ns . C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T. The measurement of $V_{OC(PP)}$ is made on test equipment with a -3 dB bandwidth of at least 5 GHz.

Figure 7. Test Circuit and Definitions for the Driver Common-Mode Output Voltage
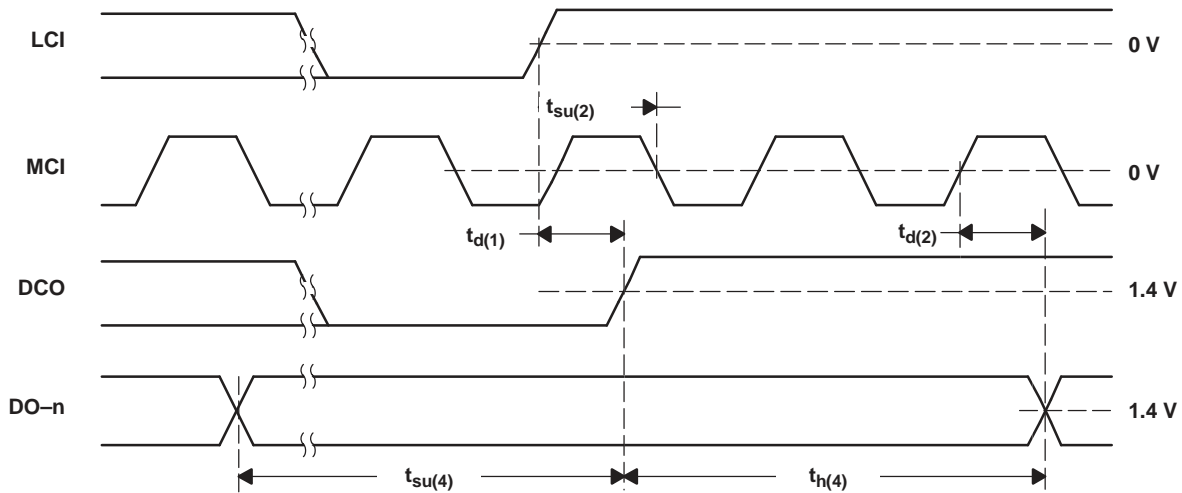
Figure 8. Data Clock and Data Output Timing Waveforms
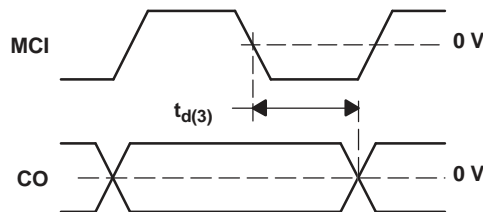
Figure 9. MCI to CO Timing Waveforms
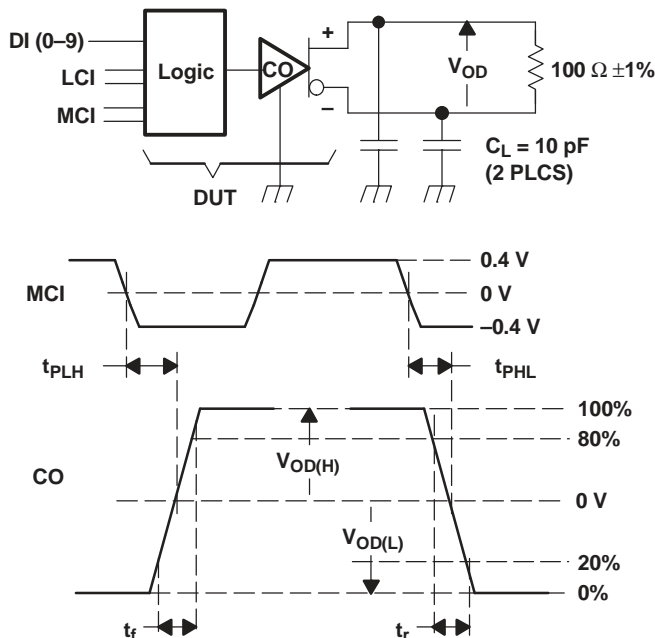
Product Folder Link(s): *SN65LVDS152*

A.   All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 100 Mpps, Pulse width = 5 ± 0.1 ns . C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 10. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal
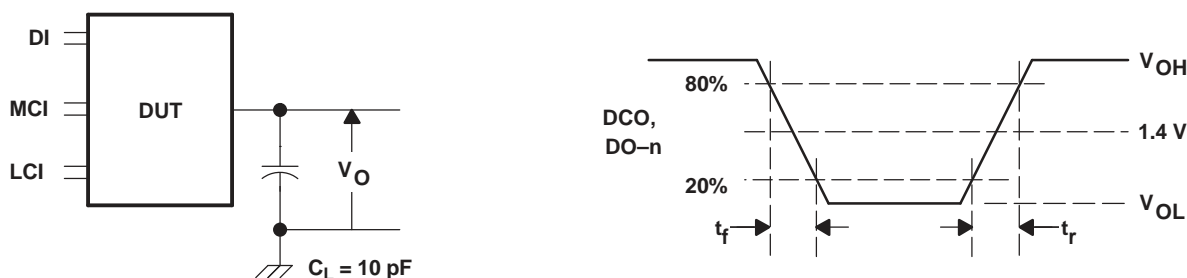
A.   All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, MCI pulse repetition rate (PRR) = 50 Mpps, Pulse width = 10 ± 0.2 ns . LCI pulse repetition rate (PRR) = 5 Mpps, pulsewidth = 100 ±2 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 11. Timing Test Circuit and Waveforms

NOTE: V_{TEST} = 2.5 V for t_{PZL} or t_{PLZ}, V_{TEST} = 0 V for t_{PZH} or t_{PHZ}. All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ±10 ns . C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

† DCO only
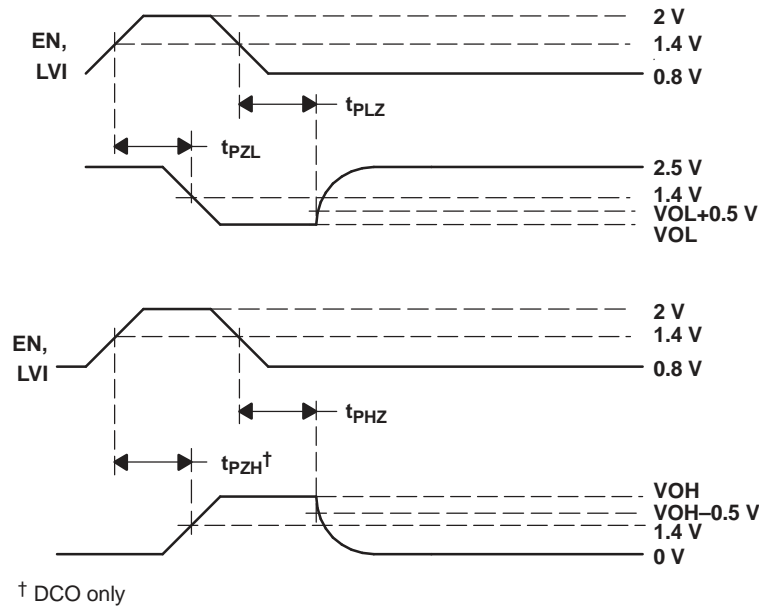
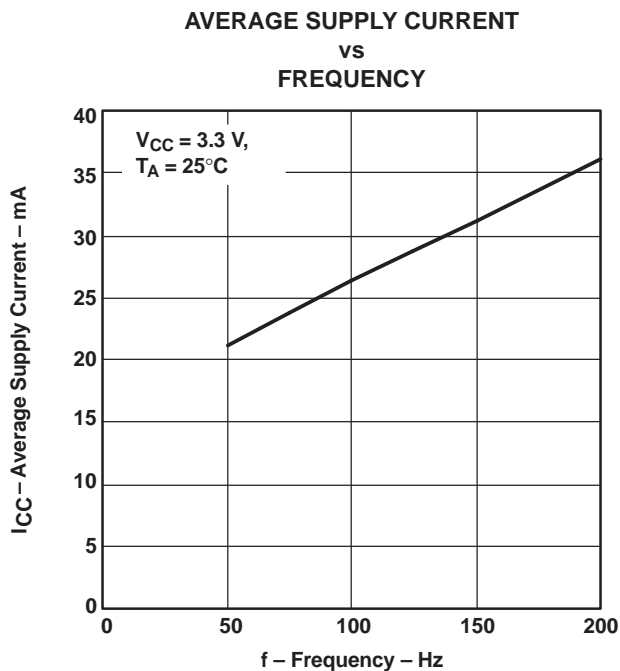**Figure 12. Enable/Disable Time Test Circuit and Waveforms**

Product Folder Link(s): *SN65LVDS152*

TYPICAL CHARACTERISTICS

AVERAGE SUPPLY CURRENT
vs
FREQUENCY

Figure 13.

REVISION HISTORY

Changes from Original (December 2000) to Revision A   **Page**

• Changed Figure 2 title From: THIS NEEDS A TITLE To: Link Clock Input and M-Clock Setup Time Waveforms 7

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65LVDS152DA	ACTIVE	TSSOP	DA	32	46	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	65LVDS152	Samples
SN65LVDS152DAR	ACTIVE	TSSOP	DA	32	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	65LVDS152	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
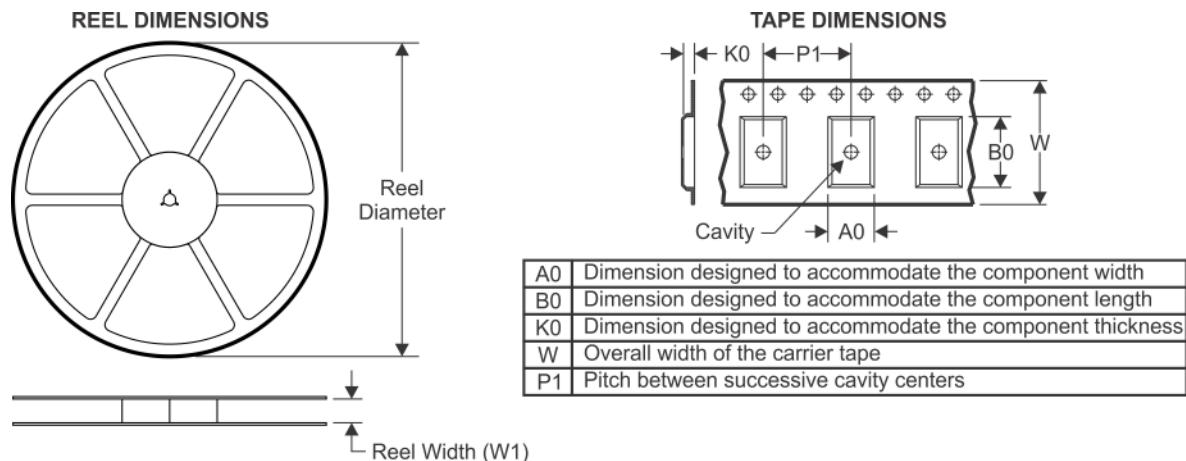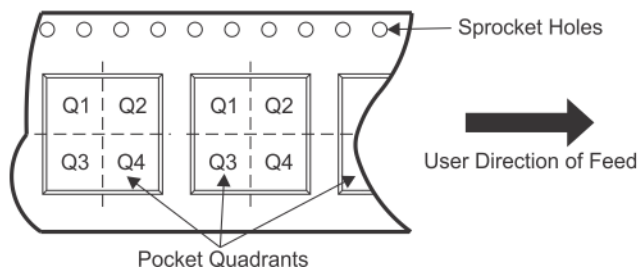
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDS152DAR	TSSOP	DA	32	2000	330.0	24.4	8.6	11.5	1.6	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDS152DAR	TSSOP	DA	32	2000	350.0	350.0	43.0

PACKAGE MATERIALS INFORMATION

TUBE
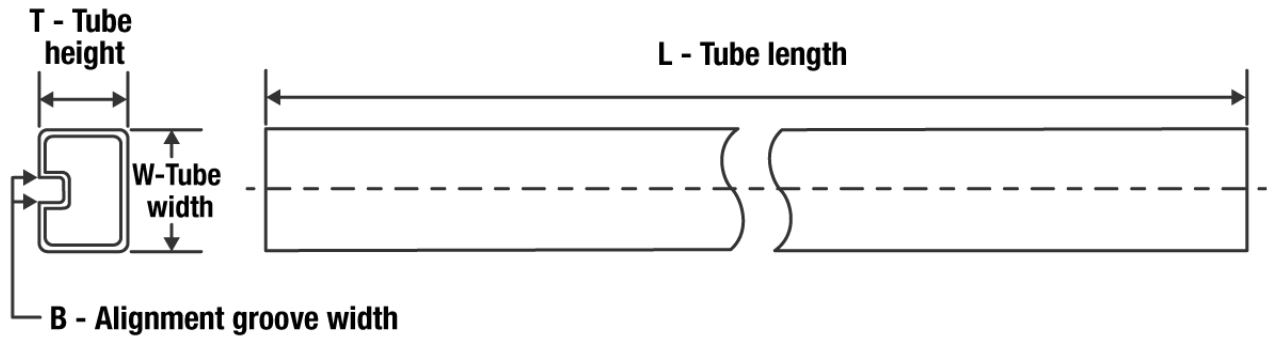
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN65LVDS152DA	DA	TSSOP	32	46	530	11.89	3600	4.9